REMARKS

The Applicants respectfully add new claim 12. Therefore claims 1-8, 12 are all the claims pending in the application (note that claims 9-11 have been withdrawn). The claims presently depending on claim 1 have been amended to now depend on claim 12.

Specification

The Applicants respectfully submit that the term "photoconductive" appearing in the present Specification is a mistranslation of "photosensitive" that repeatedly appears in the Specification of the original Japanese patent application No. 11-351226. A skilled artisan would have known that the proper term is "photosensistive".

It is clear from the present Specification that the proper term is photosensitive. Notably, as described in the present Specification , page 4, line 20, page 5, line 7 and so forth, the resin is used for insulation. This indicates that the resin is not photoconductive, since an insulation can not be conductive at the same time. It should be noted that a substance that is photoconductive has to be conductive.

Further, in the Specification, page 9, line 24 and successive lines, an aspect ratio and pattern formation is described. In addition, as taught in the Specification, page 14, line 7, exposure and development processes are executed on the resin. Such a pattern formation, exposure and development only deal with photosensitive materials. The above facts, in combination, clearly indicate that the resin is photosensitive.

Further, the Applicants respectfully submit that a person familiar with the Japanese and English languages confirmed that the appropriate term in the parent Japanese application is "photosensitive" and not "photconductive"

Newly added claim 12 is characterized in that, in a device assembly in which a plurality of devices are connected to a single electronic device and are connected to each other via resin and conductor, the plurality of devices are stacked in the direction of height (see Fig. 2, portion B, Fig. 3, portion B and Fig. 5, portion B, as well as page 7, lines 19-22 and page 9, lines 21-23). Kondo et al., the presently cited reference, does not even suggest such a configuration. Kondo et al. teaches a configuration in which a plurality of devices are arranged horizontally in a singl device plane without exception, so that the surface area increases with the increase in the number of devices. This, coupled with the fact that Kondo et al. needs a support body, clearly distinguishes Kondo et al. from the present invention capable of reducing the overall size of the assembly.

Claims 2, 4 and 6 on file, depend on claim 12 and recite additional properties of the resin and therefore are clearly distinguishable from Kondo et al., as stated above.

Claims 3, 5, 7 and 8 , depend on claim 8 and further recite limitations regarding the resin pattern and functions. Fig. 3, for example, shows a structure in which the resin above the I.D.T. electrode of a SAW filter is removed (see the specification, page 18, line 13 and successive lines). Kondo et al. does not even remotely suggest such configurations as recited in claims 3, 5, 7 and 8.

CONCLUSION

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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Date: August 6, 2003